

REMARKS

Claims 1 – 6 remain in this application. Reconsideration of this application is respectfully requested.

In the Office Action, the disclosure was objected to because of the informality that “the tow sheets” on page 8, line 32 appears to be an error. Therefore, the “tow sheets” has been amended to read --the two sheets--.

Claims 1 – 6 were rejected under 35 U.S.C. 103(a) as being unpatentable over Kataoka et al. (U.S. Patent No. 5,637,382, hereinafter “Kataoka”) in view of JP 55-153393 (hereinafter “JP ‘393”). Applicant respectfully traverses this rejection.

As the Office Action indicates, Kataoka only discloses one polyimide film that is between two copper layers.

Turning to JP ‘393, a translation of the full text of the document is submitted with this response. JP ‘393 discloses a pair of circuit boards formed with a metal foil on one surface of an insulation layer, wherein other surfaces of the insulating layer are mutually bonded by using an adhesive.

With respect to the adhesive, JP ‘393 indicates that “any adhesive is available which can bond insulating resin layers together” (see the lower left-hand section on page 3 of the Japanese document and lines 8 – 9 on page 7 of the English translation). However, JP ‘393 only discloses a thermosetting silicon-containing resin as a specific adhesive (see claim 5, the lower right-hand section of pages 3 and 4 of the Japanese document, and page 7, lines 21 – 24 and page 8, lines 15 – 18 of the English translation). Also, JP ‘393 does not disclose any specific adhesives except the thermosetting silicon-containing resin.

In contrast, the present invention discloses that the insulating layer is formed with a pair of films that are stacked by an adhesive layer that comprises an epoxy resin composition. Further, the present invention thereby has the profound effect that the mutual adhesive strength between the insulating layers is 7.0 N/cm or more by using the specific adhesive of the epoxy resin composition, which is not disclosed by JP ‘393 or made obvious by JP ‘393.

U.S. Application No. ~~11/571,084~~ -- 4 10/571,084

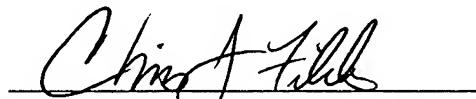
For these reasons, the combination of Kataoka and JP '393 does not result in the present invention, nor does the combination render the present invention obvious. Hence, applicant submits that claims 1 – 6 are patentable over Kataoka and JP '393. Applicant therefore respectfully requests that the Section 103(a) rejection of claims 1 – 6 as being unpatentable over Kataoka in view of JP '393 be withdrawn.

This amendment and request for reconsideration is felt to be fully responsive to the comments and suggestions of the examiner and to place this application in condition for allowance. Favorable action is requested.

Respectfully submitted,

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